This year IEEE EPS Malaysia Chapter held their AGM 100% Online. Please join me in congratulating the incoming IEEE Electronic Packaging Society (EPS) Malaysia Chapter committee that is led by Dr Yik Yee TAN.

During the 2022 IEEE Malaysia Section AGM held at Kuala Lumpur Convention Centre on 12th Feb 2022, IEEE EPS Malaysia Chapter, chaired by Dr Yik Yee Tan won the 2021 Outstanding Small Chapter Award. The purpose of the award is to recognize the outstanding performance of the small chapter among all the small chapters in Malaysia Section.

The award was presented by the IEEE Malaysia Section Chair, Dr Md Pauzi. IEEE EPS Malaysia Chapter Vice chair, Dr Eu Poh Leng received the award on behalf of the chapter (Figure 3).

Congratulations to IEEE EPS Malaysia Chapter Volunteers!!!

On 22nd Mar 2022, IEEE EPS Malaysia Chapter, held a webinar talk by UM and NXP. The webinar was moderated by IEEE EPS Malaysia Chapter Vice Chair, Dr Eu Poh Leng. The talk was collaboration between IEEE EPS Malaysia Chapter, NXP and UM. This is indeed a great collaboration between the industry and academia. There were two topics delivered: Topic 1: Flip Chip Die Attach Fluxes from Industry Perspective and Topic 2: Reliability issues related to No-Clean Flux.
As previous years, IEEE EPS Malaysia Chapter has a regular flagship “Best Engineering Student Award (BESA) for Undergraduates. This year, IEEE EPS Malaysia Chapter decided to introduce additional two (2) special awards under BESA 2022/2023, namely Prof. K.N. Seetharamu BESA (Thermal Engineering) and Azhar Aripin BESA (Simulation and Modelling).

Both Prof. Seetharamu and Azhar were the among the founding members since the earlier days of IEEE EPS Malaysia Chapter and they have contributed significantly to the chapter.

Prof. K.N. Seetharamu BESA 2022 Award:
• Must demonstrate exceptional merit, i.e. technical contribution, achievement, or innovation in the niche area of Thermal Engineering for electronic packaging.
• The submitted entry must demonstrate as outstanding work, which have won prize(s) in contest or competition or technical meeting or suite of meetings or have published in a WOS/ISI indexed journal or other related form.

Azhar Aripin BESA 2022 Award:
• Must demonstrate exceptional merit, i.e. technical contribution, achievement, or innovation in the niche area of Modelling & Simulation for electronic packaging.
• The submitted entry must demonstrate as outstanding work, which have won prize(s) in contest or competition or technical meeting or suite of meetings or have published in a WOS/ISI indexed journal or other related form.

IEEE EPS Malaysia Chapter Chair, Dr Tan proposed to use the interest from the chapter FD to support Azhar’s kids’ education, RM3,000 every year for 3 years.

On the 1st April, IEEE EPS vice chair, Dr Eu Poh Leng visited Azhar’s wife to present the education fund as well as sharing a little about the purpose of the fund.